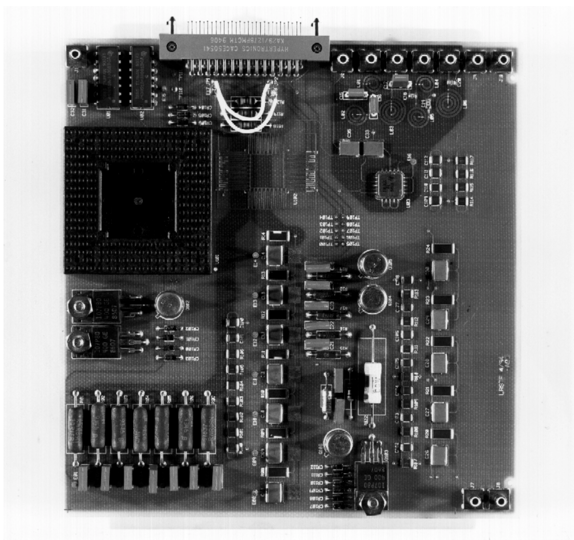
Printed Wiring Board
Surface Finishes



Cleaner Technologies Substitutes Assessment

VOLUME 1

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Disclaimer

This document was written by the grantee. It has not been through a formal external peer review process. Some information in this document was provided by individual technology vendors and has not been independently corroborated by EPA or the University of Tennessee. The use of specific trade names or the identification of specific products or processes in this document are not intended to represent an endorsement by EPA or the U.S. Government. Discussion of federal environmental statutes is intended for information purposes only; this is not an official guidance document, and should not be relied on by companies in the printed wiring board industry to determine applicable regulatory requirements.

For More Information

To learn more about the Design for the Environment (DfE) Printed Wiring Board Project or the DfE Program, please visit the DfE Program web site at:

www.epa.gov/dfe

The DfE web site also contains the document, *Cleaner Technologies Substitutes Assessment: A Methodology and Resources Guide*, which describes the basic methodology used in this assessment.

To obtain copies of DfE Printed Wiring Board Project technical reports, pollution prevention case studies, and project summaries, please contact:

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To learn more about the University of Tennessee Center for Clean Products and Clean Technologies, visit the Center's web site at:

eerc.ra.utk.edu/clean/

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Artetch Circuits Ltd.

Central Circuits Inc.

Circuit Connect Inc.

Circuit Wise Inc.

Diversified Systems

GTC Circuits Corp. (formerly General Technology Corp.)

H-R Industries

Parlex Corp.

Quality Circuits Inc.

Sanmina Corp. (formerly Altron Inc.)

Sanmina Corp. (formerly Hadco Corp.)

Solder Station One, Inc.

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